PCN Number: 201607250)03				F	PCN Date: 7/29/2016		
Title: Datasheet for LP5560								-		
Customer Contact: PCN Mana		PCN Manager	<u>er</u>				Dept:		Quality Services	
Cha	ange Type:									
	Assembly Site			Design				Wafe	r Bump Site	
	Assembly Process	Process		🛛 Data Sheet				Wafer Bump Material		
	Assembly Materials				ber change				r Bump Process	
	Mechanical Specification			Test Site				Wafer Fab Site		
	Packing/Shipping/Labeling			Test Process			<u>Ц</u>	Wafer Fab Materials		
							Wafer Fab Process			
Notification Details										
Description of Change:										
Texas Instruments Incorporated is announcing an information only notification.										
The product datasheet(s) is being updated as summarized below.										
The following change history provides further datails										
The following change history provides further details.										
	TEXAS									
	LP5560 INSTRUMENTS SNVS873D – AUGUST 2012–REVISED JUNE 2016									
Changes from Revision C (May 2013) to Revision D Page										
Added additional Applications, Device Information and Pin Configuration and Functions sections, ESD Ratings and										
Thermal Information tables, Feature Description, Device Functional Modes, Application and Implementation, Power Supply Recommendations, Layout, Device and Documentation Support, and Mechanical, Packaging, and Orderable										
Information sections										
•	 Changed R_{8JA} value from "120°C/W" to "184.3°C/W"; added additional thermal values									
The datasheet number will be changing.									Change Ter	
Device Family			Change From: SNVS873C						Change To: SNVS873D	
LP5560				311/38/30				311/30/30		
	ese changes may be		the	e datashee	t links provid	ed.				
<u>ntt</u>	<u>o://www.ti.com/pro</u>	<u>auct/LP5560</u>								
Dor	acon for Change									
	ason for Change:	t - t - t								
To more accurately reflect device characteristics.										
	ticipated impact o				-					
No anticipated impact. This is a specification change announcement only. There are no changes										
to the actual device.										
Changes to product identification resulting from this PCN:										
None.										
Product Affected:										
	5560TME/NOPB	LP5560TMX	(/N	OPB						
		2.0000110	·/ · •							

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com